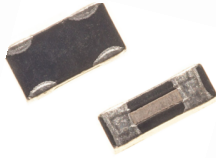


## SCCM Series



### Features

Powerful components with composite co-fired material to solve EMI problem for high speed differential signal transmission line as USB, and LVDS without distortion to high speed signal transmission.

### Applications

MIPI, MHL serial interface in mobile device.

### Product Identification

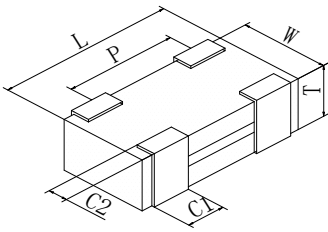
SCCM XXXXXTL - XXX  
For example:SCCM321610TL-900

### General Specifications

Test Frequency.....100MHz  
Parameters Test Temp..... 25℃  
Operation Temp.....-20℃ to +85℃  
(Including temperature Rise)  
Storage Temp.....0~40℃  
Storage Humidity.....<70% RH  
Resistance to Soldering Heat.....260℃ for 10 sec  
Temperature Rise.....40℃ Typ. at Rated Current

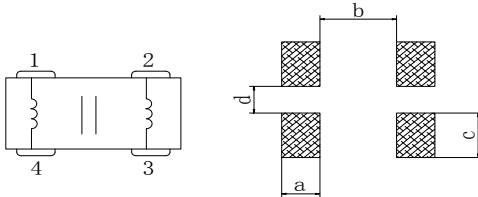
## Shape And Dimensions

## Dimensions In mm



TYPE	L	W	T	P	C1	C2	a	b	c	d
	±0.2	±0.2	±0.1	±0.2	±0.2	±0.2	Ref	Ref	Ref	Ref
321610	3.20	1.60	1.00	2.10	0.70	0.30	0.70	1.40	1.00	0.60

## Electrical Schematic & PAD Layout



## Standard Specifications

Stamp	Impedance (Ω)±25%	Test Frequency (MHz)	DCR (Ω)Max	Rated Current (mA) Max	Rated Voltage (V)	Withstand Voltage (V)	Insulation Resistance Min.(MΩ)
SCCM321610TL-900	90	100	0.50	500	10	25	200
SCCM321610TL-121	120	100	0.50	500	10	25	200

\*All the data listed in this catalogue are for reference only, JENG SHI reserves the right to alter or revise the specifications without prior notification.

\*Beyond the above specification also can meet the special requirements. Need detailed content Please to the website query or contact us.

